

ABSTRACT OF THE DISCLOSURE

Integration of annealing capability into a metal deposition tool or a chemical mechanical polishing (CMP) tool. A wafer processing apparatus includes a metal deposition tool having annealing capability. The metal deposition tool can be an
5 electroplating tool or a chemical vapor deposition tool or other metal deposition tool that deposits metal films, such as copper, onto silicon substrates for integrated circuit manufacturing. An annealing chamber is integrated into the metal deposition tool so that annealing of the metal film can be controlled such that the copper is consistently stabilized in preparation for a chemical mechanical polishing process. Alternatively, an annealing
10 chamber can be integrated into a CMP tool.